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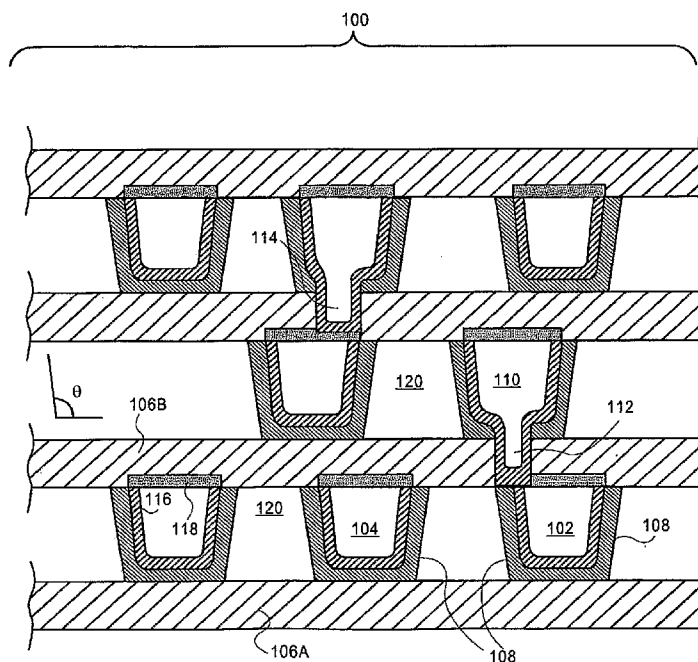
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(54) Title: DIELECTRIC SPACERS FOR METAL INTERCONNECTS AND METHOD TO FORM THE SAME



(57) Abstract: Dielectric spacers for a plurality of metal interconnects and a method to form such dielectric spacers are described. In one embodiment, the dielectric spacers are adjacent to neighboring metal interconnects having flared profiles and are discontinuous from one another. In another embodiment, the dielectric spacers provide a region upon which un-landed vias may effectively land.

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